



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

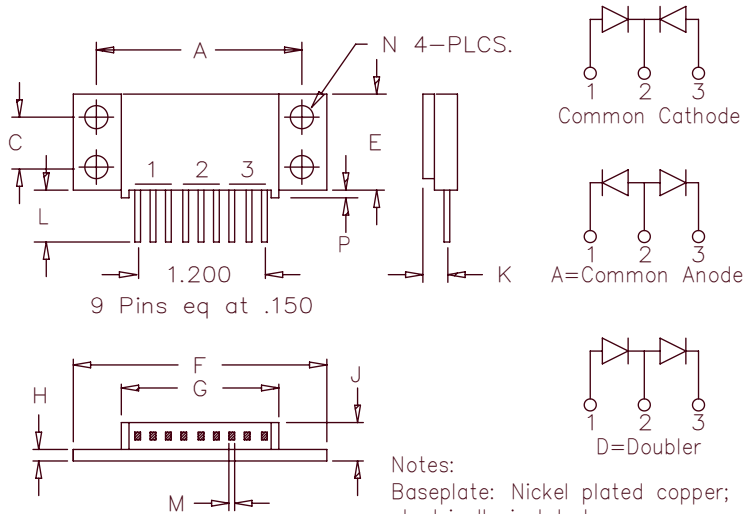
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Schottky Powermod FST6080 — FST60100



Dim.	Inches		Millimeter		Notes
	Minimum	Maximum	Minimum	Maximum	
A	1.995	2.005	50.67	50.93	
C	0.495	0.506	12.57	12.83	
E	0.990	1.010	25.15	25.65	
F	2.390	2.410	60.71	61.21	
G	1.490	1.510	37.85	38.35	
H	0.120	0.130	3.05	3.30	
J	---	0.400	---	10.16	
K	0.240	0.260	6.10	6.60	to Lead \varnothing
L	0.490	0.510	12.45	12.95	
M	0.040	.050	1.02	1.27	Square
N	0.175	0.195	4.45	4.95	Dia
P	0.032	0.052	0.81	1.32	

Microsemi Catalog Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
FST6080*	80V	80V
FST6090*	90V	90V
FST60100*	100V	100V

*Add the Suffix A for Common Anode, D for Doubler

- Schottky barrier rectifier
- Guard ring for reverse protection
- VRRM – 80 to 100 Volts
- High surge capacity
- Reverse energy tested
- Electrically isolated baseplate
- ROHS Compliant

Electrical Characteristics

Average forward current per pkg	$I_{F(AV)}$ 120 Amps	$T_C = 130^\circ\text{C}$, Square wave, $R_{\theta JC} = 0.6^\circ\text{C/W}$
Average forward current per leg	$I_{F(AV)}$ 60 Amps	$T_C = 130^\circ\text{C}$, Square wave, $R_{\theta JC} = 1.0^\circ\text{C/W}$
Maximum surge current per leg	I_{FSM} 1200 Amps	8.3 ms, half sine $T_J = 175^\circ\text{C}$
Max repetitive peak reverse current per leg	$R(OV)$ 2 Amps	$f = 1 \text{ KHz}$, 25°C , 1 μsec Square wave
Max peak forward voltage per leg	V_{FM} .68 Volts	$I_{FM} = 60\text{A}$: $T_J = 175^\circ\text{C}^*$
Max peak forward voltage per leg	V_{FM} .86 Volts	$I_{FM} = 60\text{A}$: $T_J = 25^\circ\text{C}^*$
Max peak reverse current per leg	I_{RM} 30 mA	V_{RRM} , $T_J = 125^\circ\text{C}^*$
Max peak reverse current per leg	I_{RM} 2 mA	V_{RRM} , $T_J = 25^\circ\text{C}$
Typical junction capacitance per leg	C_J 1500 pF	$V_R = 5.0\text{V}$, $T_J = 25^\circ\text{C}$

*Pulse test: Pulse width 300 μsec , Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range	T_{STG}	-55°C to 175°C
Operating junction temp range	T_J	-55°C to 175°C
Maximum thermal resistance per leg	$R_{\theta JC}$	1.0°C/W Junction to case
Maximum thermal resistance per pkg	$R_{\theta JC}$	0.6°C/W Junction to case
Typical thermal resistance (greased)	$R_{\theta CS}$	0.1°C/W Case to sink
Mounting torque		15 – 20 inch pounds maximum
Weight		2.5 ounces (71 grams) typical

FST6080 — FST60100

Figure 1
Typical Forward Characteristics — Per Leg

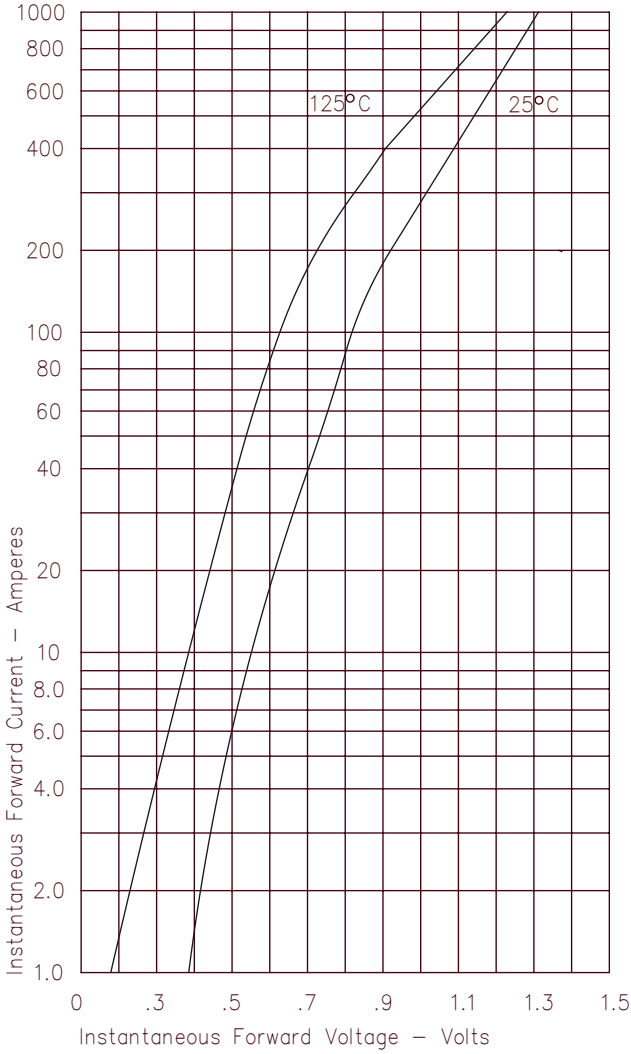


Figure 3
Typical Junction Capacitance — Per Leg

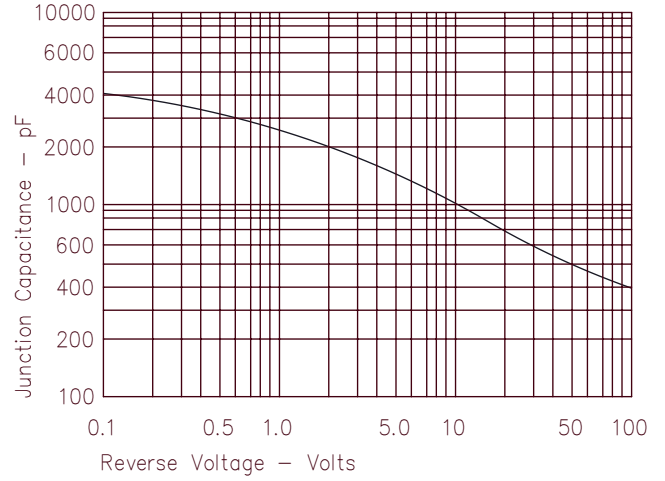


Figure 4
Forward Current Derating — Per Leg

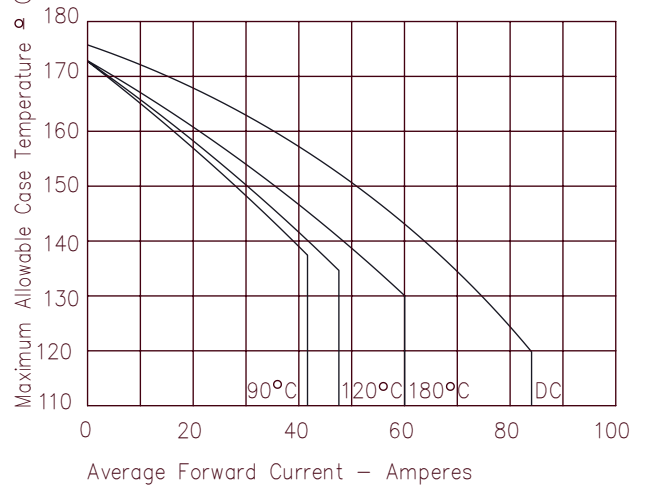


Figure 2
Typical Reverse Characteristics — Per Leg

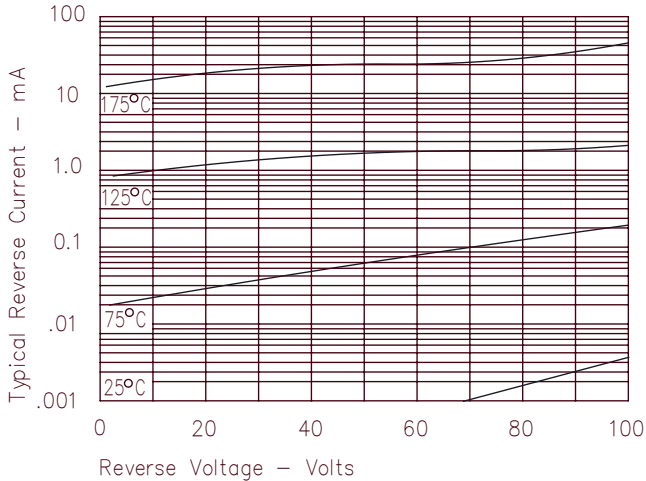
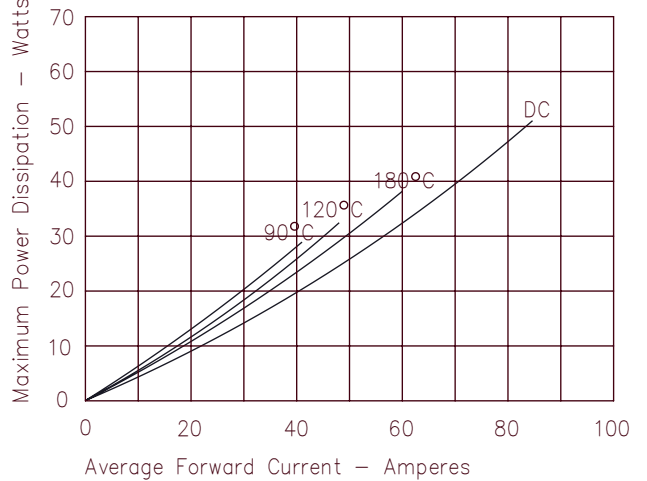


Figure 5
Maximum Forward Power Dissipation — Per Leg



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